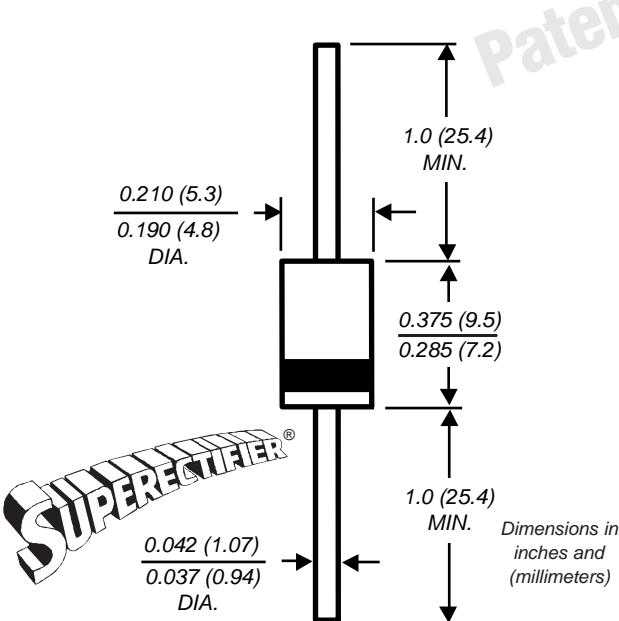




## Glass Passivated Ultrafast Rectifier

 Reverse Voltage 50 to 400 V  
 Forward Current 5.0 A

**GP20**


\*Glass Encapsulation technique is covered by  
 Patent No. 3,996,602, brazed-lead assembly to Patent No. 3,930,306

### Features

- Plastic package has Underwriters Laboratories Flammability Classification 94V-0
- Cavity-free glass passivated junction
- Ultrafast recovery time for high efficiency
- Low forward voltage, high current capability
- Low leakage current
- High surge current capability
- High temperature metallurgically bonded construction
- High temperature soldering guaranteed:  
 300°C/10 seconds, 0.375" (9.5mm) lead length,  
 5 lbs. (2.3kg) tension

### Mechanical Data

**Case:** Molded plastic over solid glass body

**Terminals:** Axial leads, solderable per MIL-STD-750,  
 Method 2026

**Polarity:** Color band denotes cathode end

**Mounting Position:** Any

**Weight:** 0.03 oz., 0.8 g

### Maximum Ratings & Thermal Characteristics

 Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	EGP50A	EGP50B	EGP50C	EGP50D	EGP50F	EGP50G	Unit
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	150	200	300	400	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	105	140	210	280	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	150	200	300	400	V
Maximum average forward rectified current 0.375" (9.5mm) lead length at T <sub>L</sub> = 55°C	I <sub>F(AV)</sub>	5.0						A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	150						A
Typical thermal resistance (Note 1)	R <sub>θJA</sub> R <sub>θJL</sub>	20 5.0						°C/W
Operating and storage temperature range	T <sub>J,TSTG</sub>	-65 to +150						°C

### Electrical Characteristics

 Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	EGP50A	EGP50B	EGP50C	EGP50D	EGP50F	EGP50G	Unit		
Maximum instantaneous forward voltage at 5.0A	V <sub>F</sub>	0.95			1.25		V			
Maximum DC reverse current at rated DC blocking voltage	I <sub>R</sub>	T <sub>A</sub> = 25°C T <sub>A</sub> = 125°C	5.0 50			μA				
Maximum reverse recovery time at I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A, I <sub>rr</sub> = 0.25A	t <sub>rr</sub>	50			ns					
Typical junction capacitance at 4.0V, 1MHz	C <sub>J</sub>	95			75		pF			

**Note:** (1) Thermal resistance from junction to ambient, and from junction to lead at 0.375" (9.5mm) lead length, P.C.B. mounted

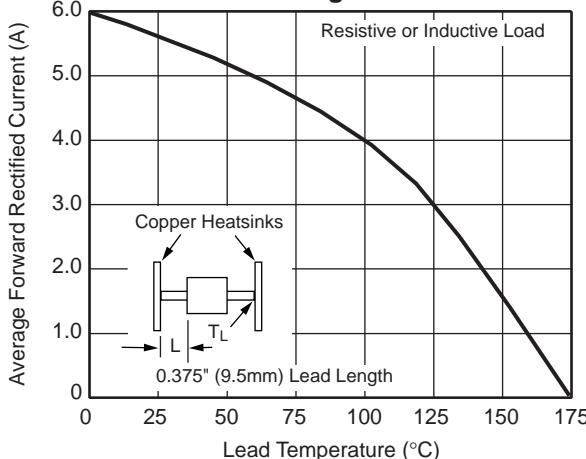
# EGP50A thru EGP50G



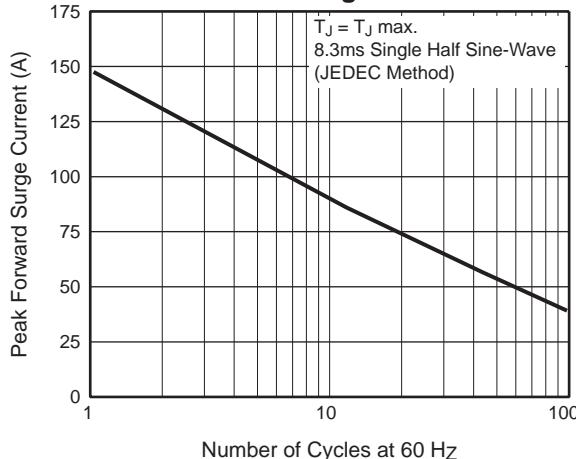
Vishay Semiconductors  
formerly General Semiconductor

## Ratings and Characteristic Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

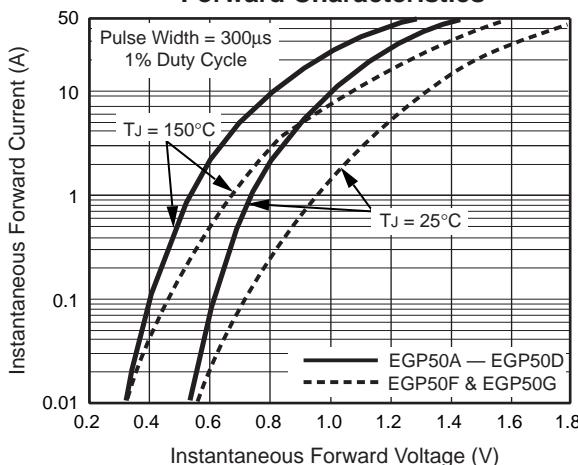
**Fig. 1 – Maximum Forward Current Derating Curve**



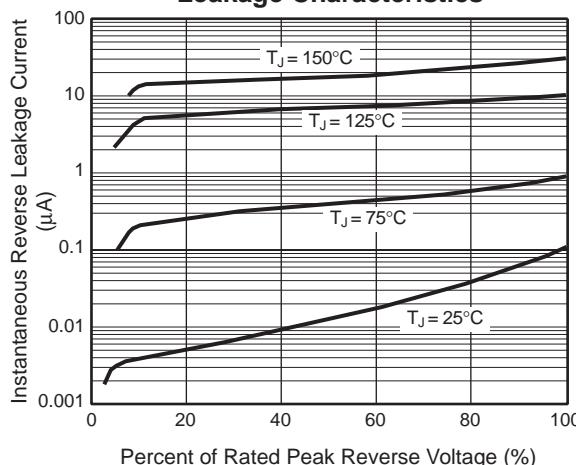
**Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current**



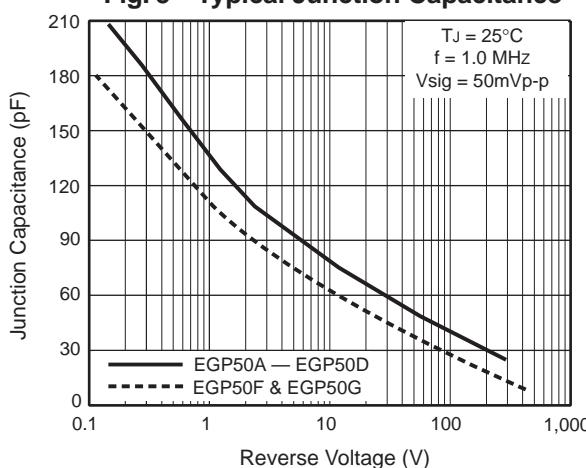
**Fig. 3 – Typical Instantaneous Forward Characteristics**



**Fig. 4 – Typical Reverse Leakage Characteristics**



**Fig. 5 – Typical Junction Capacitance**



**Fig. 6 – Typical Transient Thermal Impedance**

